

HMHAA280

AC Input, Half Pitch Mini-Flat Package 4-Pin Optocoupler

Features

- Compact 4-pin package (2.4mm maximum standoff height)
- Half pitch leads for optimum board space savings
- Current Transfer Ratio: 50–600%
- Available in tape and reel quantities of 2500
- CSA (File #1201524), UL (File #E90700) and VDE (File #136480) certified

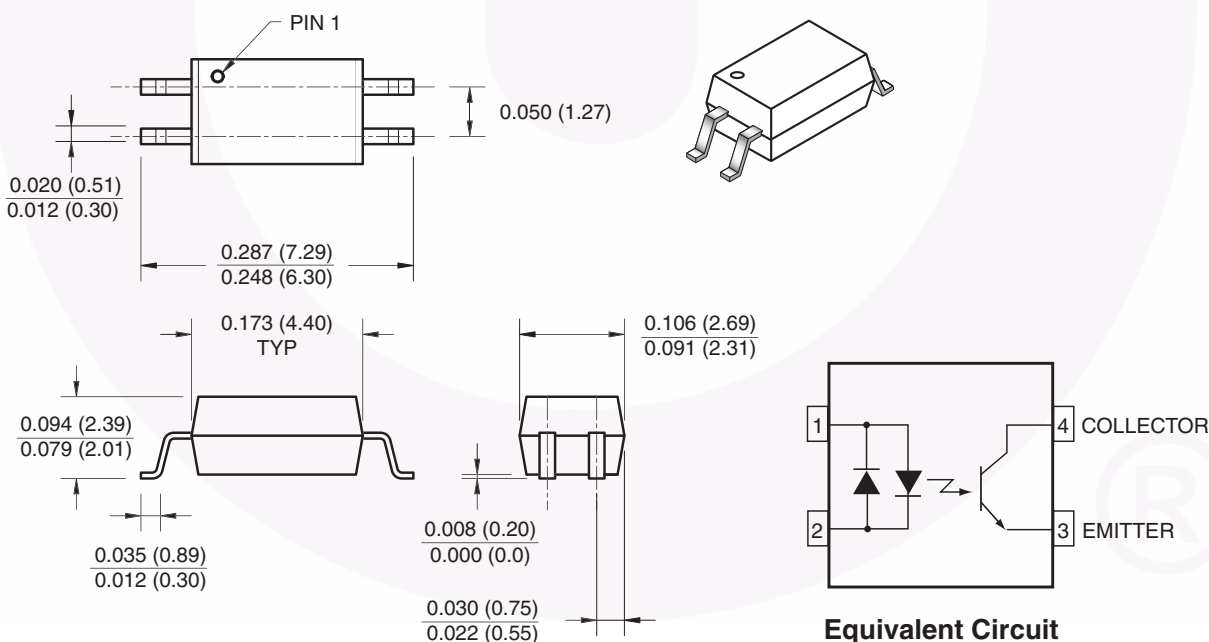
Applications

- AC line monitor
- Unknown polarity DC sensor
- Telephone line receiver

Description

The HMHAA280 series consists of two gallium arsenide infrared emitting diodes, connected in inverse parallel, driving a single silicon phototransistor in a compact 4-pin mini-flat package. The lead pitch is 1.27mm.

Package Dimensions



Note:

All dimensions are in inches (millimeters)

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Value	Units
TOTAL PACKAGE			
T_{STG}	Storage Temperature	-55 to +125	$^\circ\text{C}$
T_{OPR}	Operating Temperature	-55 to +100	$^\circ\text{C}$
EMITTER			
I_F (avg)	Continuous Forward Current	50	mA
I_F (pk)	Peak Forward Current (1 μs pulse, 300pps.)	1	A
V_R	Reverse Input Voltage	6	V
P_D	Power Dissipation	60	mW
	Derate linearly (above 25°C)	0.6	mW/ $^\circ\text{C}$
DETECTOR			
	Continuous Collector Current	50	mA
P_D	Power Dissipation	150	mW
	Derate linearly (above 25°C)	1.5	mW/ $^\circ\text{C}$
V_{CEO}	Collector-Emitter Voltage	80	V
V_{ECO}	Emitter-Collector Voltage	7	V

Electrical Characteristics ($T_A = 25^\circ\text{C}$)

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Unit
INDIVIDUAL COMPONENT CHARACTERISTICS						
Emitter						
V _F	Forward Voltage	I _F = ±5mA			1.4	V
I _R	Reverse Current	V _R = 5V			5	µA
Detector						
BV _{CEO}	Breakdown Voltage Collector to Emitter	I _C = 0.5mA, I _F = 0	80			V
BV _{ECO}	Emitter to Collector	I _E = 100µA, I _F = 0	7			
I _{CEO}	Collector Dark Current	V _{CE} = 80V, I _F = 0			100	nA
C _{CE}	Capacitance	V _{CE} = 0V, f = 1MHz		10		pF
TRANSFER CHARACTERISTICS						
CTR	DC Current Transfer Ratio	I _F = ±5mA, V _{CE} = 5V	50		600	%
	CTR Symmetry	I _F = ± 5mA, V _{CE} = 5V	0.33		3.0	
V _{CE (SAT)}	Saturation Voltage	I _F = ± 8mA, I _C = 2.4mA			0.4	V
t _r	Rise Time (Non-Saturated)	I _C = 2mA, V _{CE} = 5V, R _L = 100Ω		3		µs
t _f	Fall Time (Non-Saturated)	I _C = 2mA, V _{CE} = 5V, R _L = 100Ω		3		
ISOLATION CHARACTERISTICS						
V _{ISO}	Steady State Isolation Voltage	1 Minute	3750			VRMS

*All typicals at $T_A = 25^\circ\text{C}$

Typical Performance Characteristics

Fig. 1 Forward Current vs. Forward Voltage

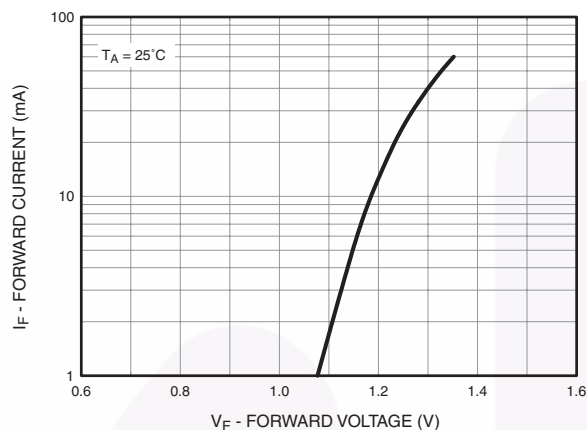


Fig. 2 Collector Current vs. Forward Current

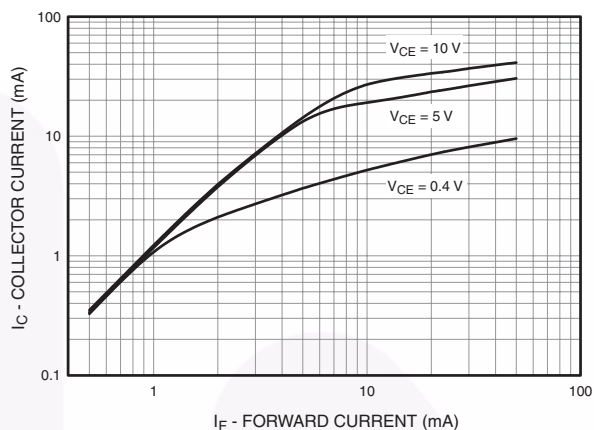


Fig. 3 Current Transfer Ratio vs. Forward Current

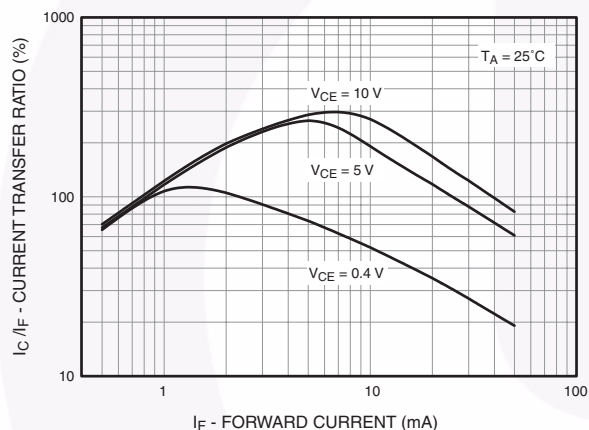


Fig. 4 Normalized CTR vs. Temperature

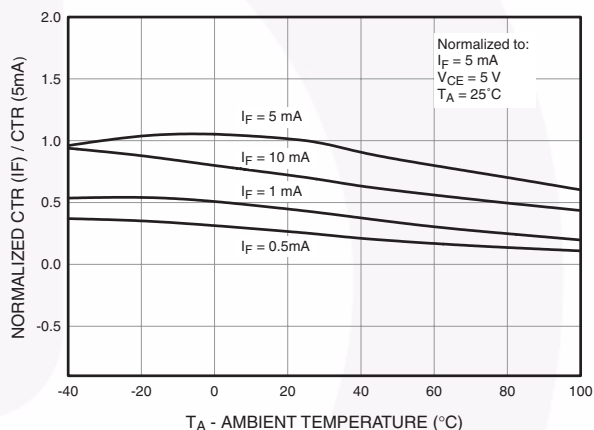
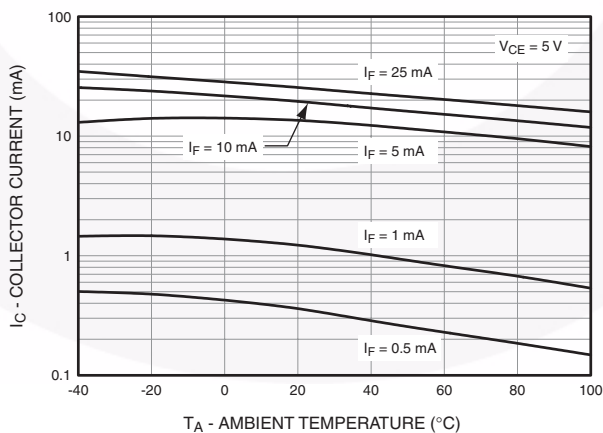


Fig. 5 Collector Current vs. Temperature



Typical Performance Characteristics (Continued)

Fig. 6 Collector Current vs. Collector-Emitter Voltage

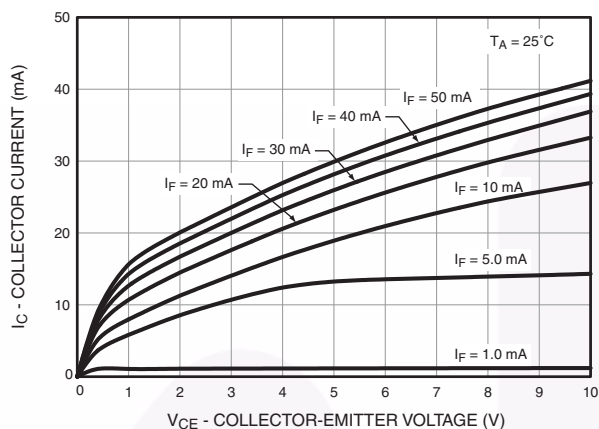


Fig. 7 Collector Current vs. Collector-Emitter Voltage

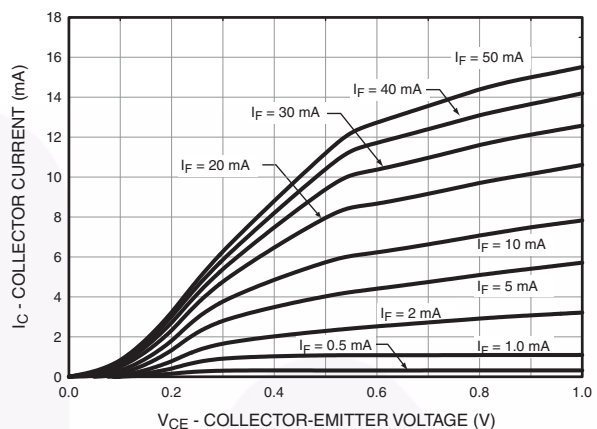


Fig. 8 Collector Dark Current vs. Temperature

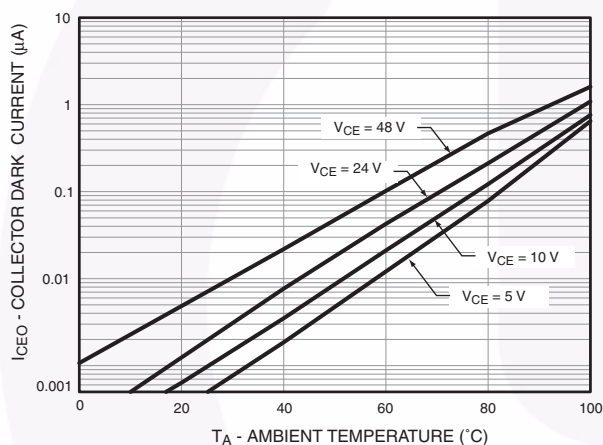


Fig. 9 Switching Time vs. Load Resistance

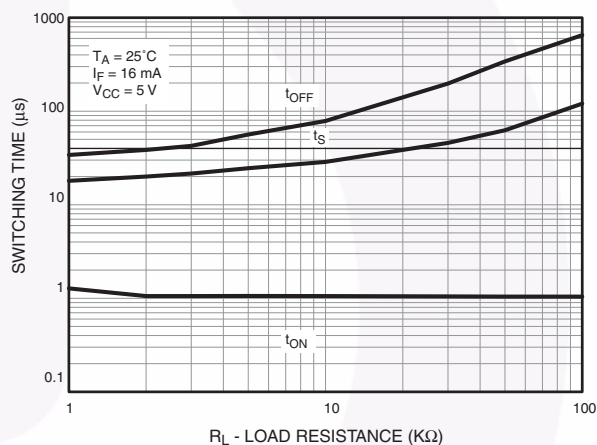
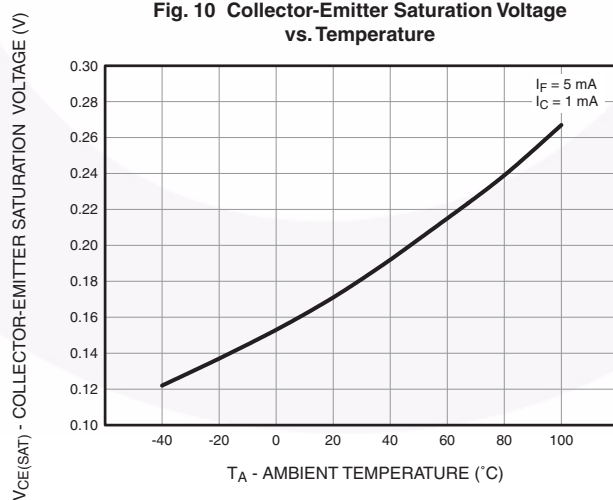


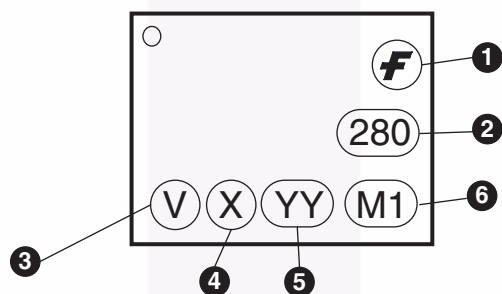
Fig. 10 Collector-Emitter Saturation Voltage vs. Temperature



Ordering Information

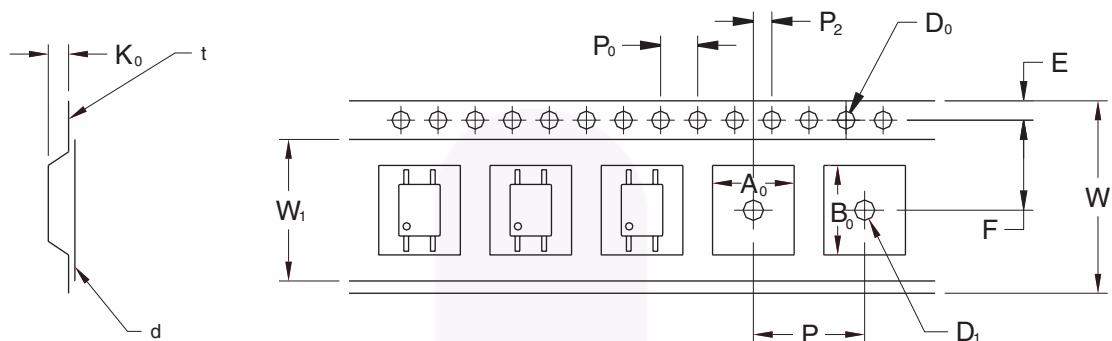
Option	Description
V	VDE Approved
R2	Tape and Reel (2500 units)
R2V	Tape and Reel (2500 units) and VDE Approved

Marking Information



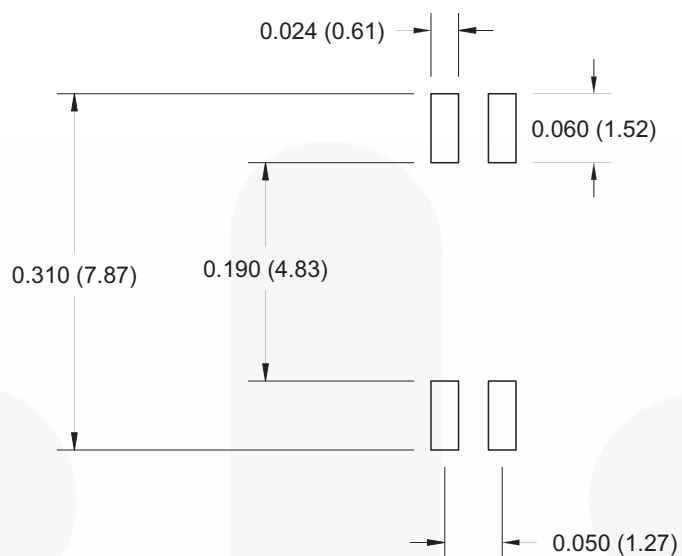
Definitions	
1	Fairchild logo
2	Device number
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)
4	One digit year code
5	Two digit work week ranging from '01' to '53'
6	Assembly package code

Tape and Reel Dimensions

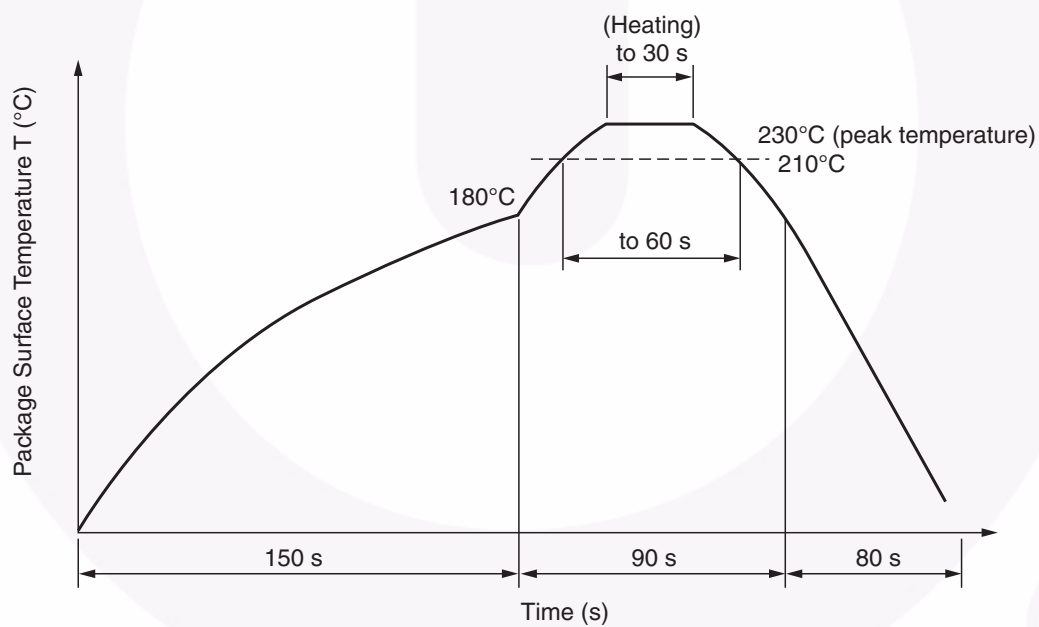


		1.27 Pitch
Description	Symbol	Dimensions (mm)
Tape Width	W	12.00 +0.30/-0.10
Tape Thickness	t	0.30 ±0.05
Sprocket Hole Pitch	P ₀	4.00 ±0.10
Sprocket Hole Diameter	D ₀	1.50 +0.10/-0.0
Sprocket Hole Location	E	1.75 ±0.10
Pocket Location	F	5.50 ±0.10
	P ₂	2.00 ±0.10
Pocket Pitch	P	8.00 ±0.10
Pocket Dimension	A ₀	2.80 ±0.10
	B ₀	7.30 ±0.10
	K ₀	2.30 ±0.10
Pocket Hole Diameter	D ₁	1.50 Min.
Cover Tape Width	W ₁	9.20
Cover Tape Thickness	d	0.065 ±0.010
Max. Component Rotation or Tilt		10° Max.
Devices Per Reel		2500
Reel Diameter		330mm (13")

Footprint Drawing for PCB Layout



Reflow Profile0

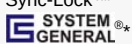


- Peak reflow temperature: 230°C (package surface temperature) for 30 seconds
- Time of temperature higher than 210°C: 60 seconds or less
- One time soldering reflow is recommended



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Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
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Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.

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